

非硅型导热薄材 XK-FN10

简介:

XK-FN 非硅型导热薄材主要应用于硅氧烷敏感应用,在车灯,镜头,雷射装置,通讯器材,航天设备等有显著差异,没有硅氧烷挥发影响光学性质与电学性质可能,XK-FN 系列为高分子材料混掺陶瓷填料,以玻璃纤维布为基材,可以确保尺寸安定性,施工容易.

特质:

- 1.采用 Polyester 树脂为基底
- 2.无硅氧烷挥发

应用:

LED 车灯
光学精密设备



| | unit | XK-FN10 | Method |
|---------------------------|----------------------|-------------------|------------|
| Reinforcement Carrier | | Fiberglass | visual |
| Thickness | mm | 0.25 | ASTM D374 |
| Specific Gravity | g/cm ³ | 2 | ASTM D792 |
| Hardness | Shore A | 90 | ASTM D2240 |
| Thermal impedance | °Cin ² /W | 0.68 | ASTM D5470 |
| Thermal Conductivity | W/mK | 1 | HOT DISK |
| Volume Resistivity | Ωcm | >10 ¹³ | ASTM D257 |
| Breakdown Voltage | KV/mm | >3.5 | ASTM D149 |
| Dielectric Constant | 1 | 5 | ASTM D150 |
| Application temperature | °C | -30~125 | |
| Tensile strength | psi | >1000 | ASTM D149 |
| Elongation | % | 30 | ASTM D149 |
| Siloxane Volatiles D4~D20 | % | <0.01 | GC-FID |
| Flammability | UL94 | V-0 | UL94 |